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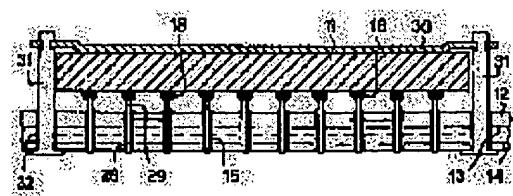
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(54) ELECTRICAL ASSEMBLY, AND METHOD TO CARRY OUT ELECTRICAL CONNECTION BETWEEN ELECTRICAL PART AND CIRCUIT BOARD

(57) Abstract:

PURPOSE: To carry out an improve connection in an electrical assembly, which avoids the use of reflow solder.

CONSTITUTION: An electrical assembly composes an electrical part 11 with an array of contact projections 18. The part 11 is installed on a multilayer printed circuit board 12. Plural conductive pins 28 are inserted in the holes of the printed circuit board 12. The sharp tips 29 of the pins 28 protrude on the printed circuit board 12 and contact electrically with the projections 18 of the part 11.



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